

N-CHANNEL ENHANCEMENT MODE FIELD MOSFET
Product Summary

| $V_{(BR)DSS}$ | $R_{DS(ON)}$ | Package | I_S $T_A = +25^\circ C$ |
|---------------|--------------------------------|--------------|------------------------------|
| 24V | 26m Ω @ $V_{GS} = 4.5V$ | X1-WLB1818-4 | 6.0A |

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) with thin WLCSP packaging process and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Battery Management
- Load Switch
- Battery Protection

Features

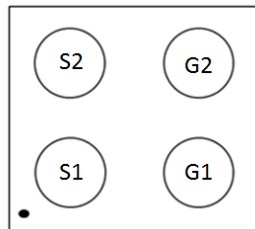
- Built-in G-S Protection Diode Against ESD 2kV HBM
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

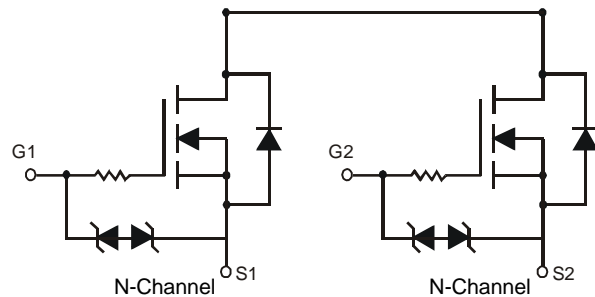
- Case: X1-WLB1818-4
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram



X1-WLB1818-4



Top View



Equivalent Circuit

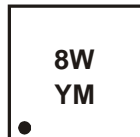
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|--------------|-------------------|
| DMN2023UCB4-7 | X1-WLB1818-4 | 3,000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

X1-WLB1818-4



8W = Product Type Marking Code
 YM = Date Code Marking
 Y or \bar{Y} = Year (ex: Y = 2011)
 M or \bar{M} = Month (ex: 9 = September)

Date Code Key

| Year | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 |
|------|------|------|------|------|------|------|------|
| Code | Y | Z | A | B | C | D | E |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | | Symbol | Value | Units |
|--|-----------------|------------------------|------------------|-------|-------|
| Drain-Source Voltage | | | V _{SSS} | 24 | V |
| Gate-Source Voltage (Note 5) | | | V _{GSS} | ±12 | V |
| Continuous Source Current @ T _A = +25°C (Note 6) | Steady State | T _A = +25°C | I _S | 6.0 | A |
| | | T _A = +70°C | | 4.8 | |
| Pulsed Source Current @ T _A = +25°C (Notes 6 & 7) | | | I _{SM} | 20 | A |

Thermal Characteristics

| Characteristic | Symbol | Value | Units |
|---|-----------------------------------|-------------|-------|
| Power Dissipation, @ T _A = +25°C (Note 6) | P _D | 1.45 | W |
| Thermal Resistance, Junction to Ambient @ T _A = +25°C (Note 6) | R _{θJA} | 88.21 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|---------------------|------|------|------|------|---|
| OFF CHARACTERISTICS (Note 8) | | | | | | |
| Source to Source Breakdown Voltage T _J = +25°C | V _{(BR)SS} | 24 | — | — | V | I _S = 1mA, V _{GS} = 0V TEST CIRCUIT 1 |
| Zero Gate Voltage Source Current T _J = +25°C | I _{SSS} | — | — | 1.0 | µA | V _{SS} = 20V, V _{GS} = 0V TEST CIRCUIT 1 |
| Gate-Body Leakage | I _{GSS} | — | — | ±10 | µA | V _{GS} = ±8V, V _{DS} = 0V TEST CIRCUIT 2 |
| ON CHARACTERISTICS (Note 8) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 0.5 | — | 1.3 | V | V _{SS} = 10V, I _S = 1.0mA TEST CIRCUIT 3 |
| Static Source -Source On-Resistance | R _{SS(ON)} | 17 | 21.5 | 25.5 | mΩ | V _{GS} = 6.5V, I _S = 3.0A TEST CIRCUIT 5 |
| | | 17.5 | 22 | 26 | | V _{GS} = 4.5V, I _S = 3.0A TEST CIRCUIT 5 |
| | | 18.5 | 23 | 27 | | V _{GS} = 4.0V, I _S = 3.0A TEST CIRCUIT 5 |
| | | 19 | 23.5 | 29 | | V _{GS} = 3.7V, I _S = 3.0A TEST CIRCUIT 5 |
| | | 19.5 | 24 | 33 | | V _{GS} = 3.1V, I _S = 3.0A TEST CIRCUIT 5 |
| | | 21.5 | 27 | 40 | | V _{GS} = 2.5V, I _S = 3.0A TEST CIRCUIT 5 |
| Forward Transfer Admittance | Y _{fs} | — | 12 | — | S | V _{SS} = 10V, I _S = 3.0A TEST CIRCUIT 4 |
| Body Diode Forward Voltage | V _{F(S-S)} | — | 0.7 | 1 | V | I _F = 3.0A, V _{GS} = 0V, TEST CIRCUIT 6 |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | |
| Input Capacitance | C _{iss} | — | 2564 | 3333 | pF | V _{SS} = 10V, V _{GS} = 0V, f = 1.0MHz TEST CIRCUIT 7 |
| Output Capacitance | C _{oss} | — | 197 | 275 | | |
| Reverse Transfer Capacitance | C _{rss} | — | 183 | 260 | | |
| Total Gate Charge | Q _g | — | 29 | 37 | nC | V _{GS} = 4.5V, V _{SS} = 10V, I _S = 6A TEST CIRCUIT 9 |
| Turn-On Delay Time | t _{D(on)} | — | 10 | 15 | ns | V _{DD} = 10V, R _L = 3.33Ω, I _S = 3.0A TEST CIRCUIT 8 |
| Turn-On Rise Time | t _r | — | 20 | — | ns | |
| Turn-Off Delay Time | t _{D(off)} | — | 75 | 110 | ns | |
| Turn-Off Fall Time | t _f | — | 29 | — | ns | |

- Notes:
5. AEC-Q101 VGS maximum is ±9.6V.
 6. Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.
 7. Repetitive rating, pulse width limited by junction temperature.
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to production testing.

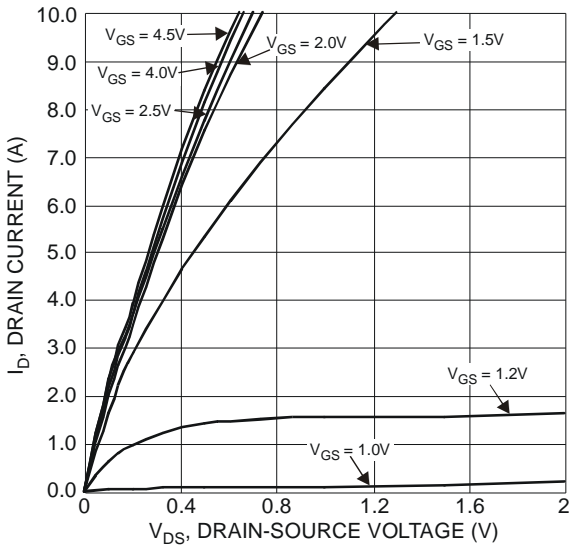


Figure 1 Typical Output Characteristics

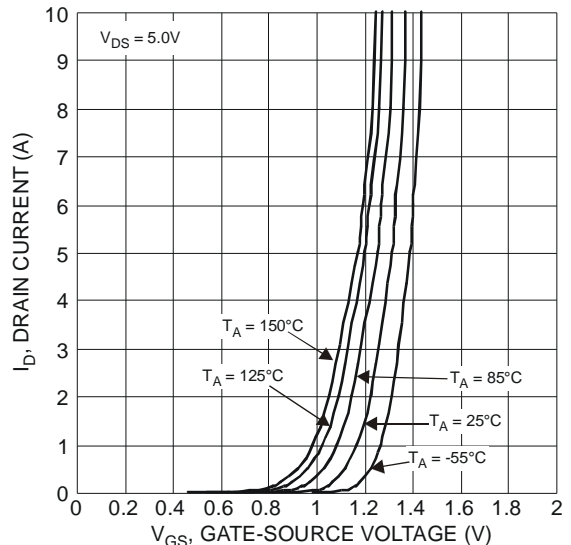


Figure 2 Typical Transfer Characteristics

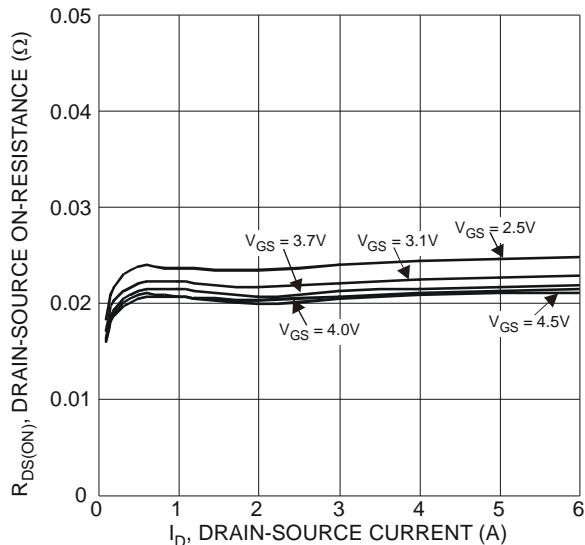


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

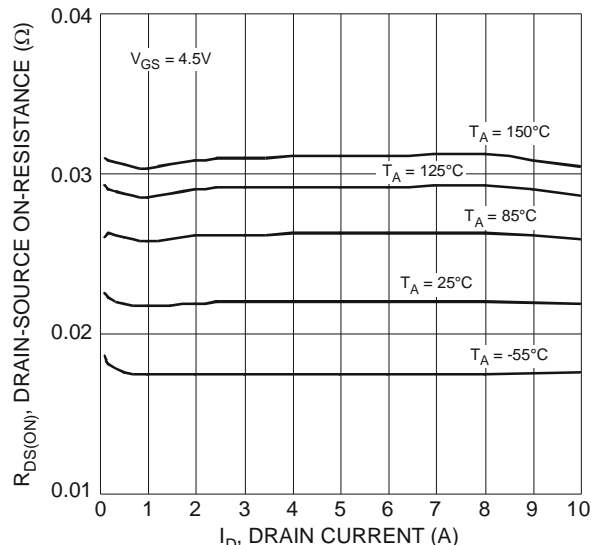


Figure 4. Typical On-Resistance vs. Drain Current and Temperature

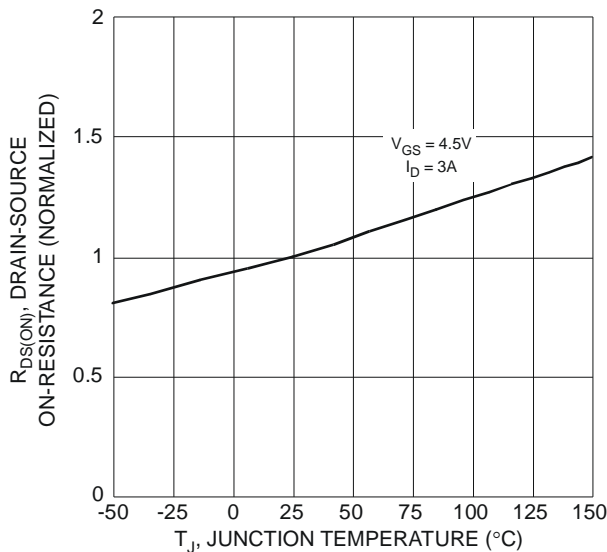


Figure 5 On-Resistance Variation with Temperature

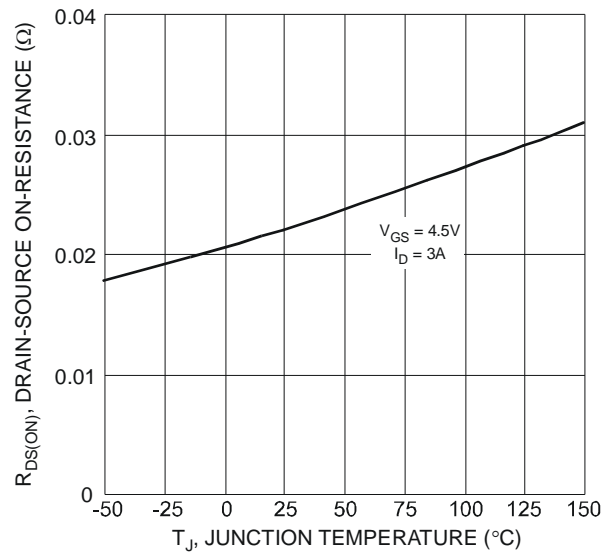


Figure 6 On-Resistance Variation with Temperature

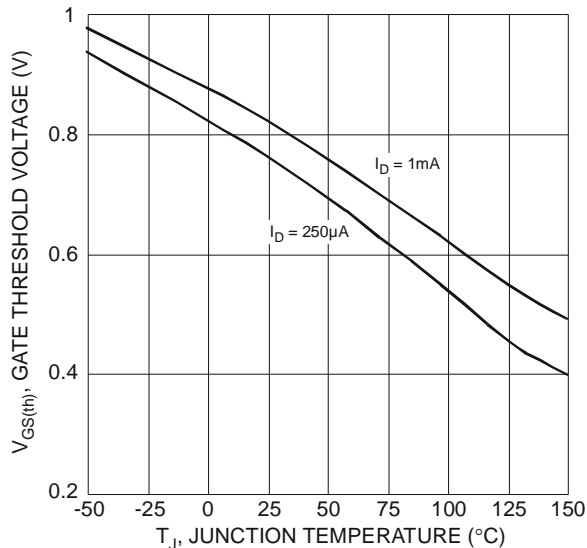


Figure 7 Gate Threshold Variation vs. Ambient Temperature

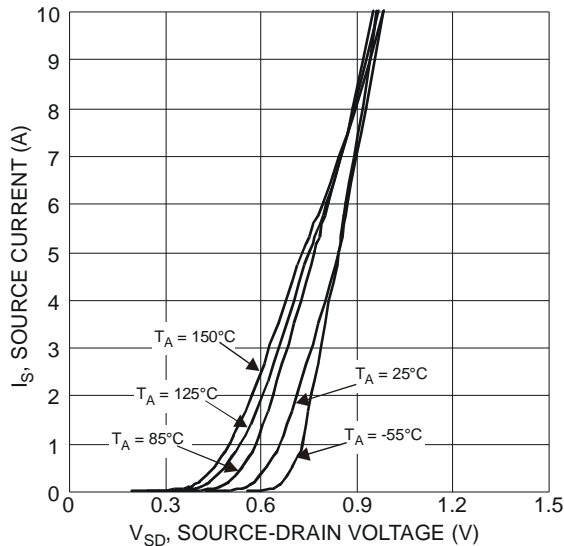


Figure 8 Diode Forward Voltage vs. Current

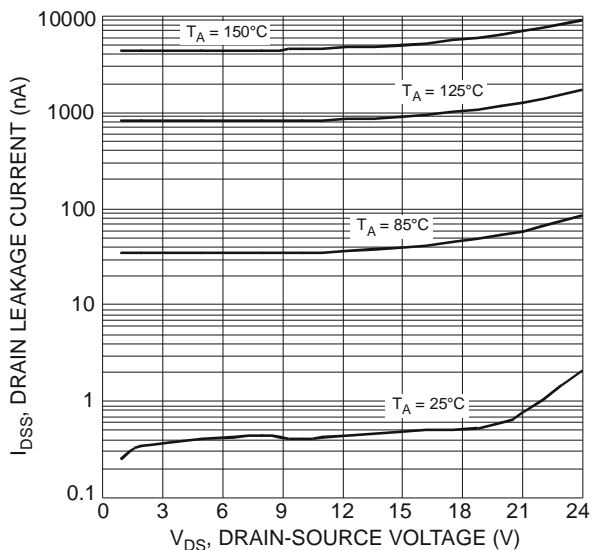


Figure 9 Typical Drain-Source Leakage Current vs. Voltage

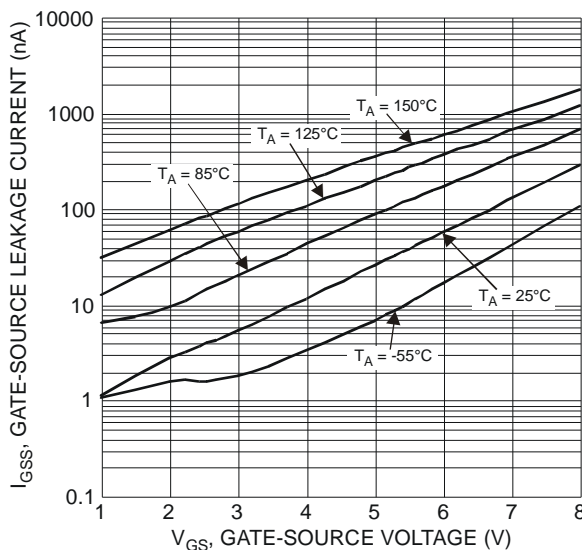


Figure 10 Typical Gate-Source Leakage Current vs. Gate-Source Voltage

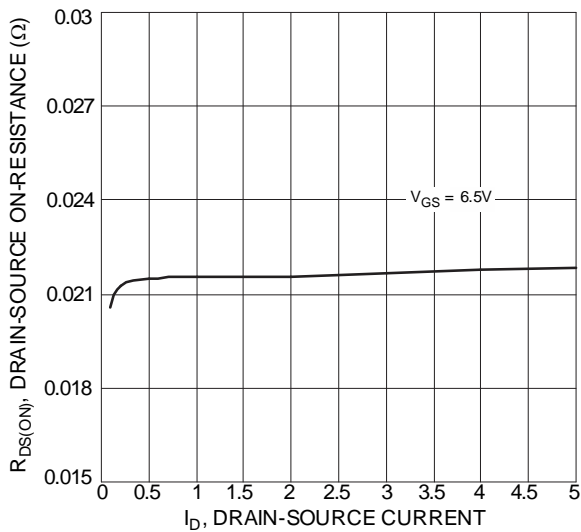


Figure 11 Typical On-Resistance vs. Drain Current and Gate Voltage

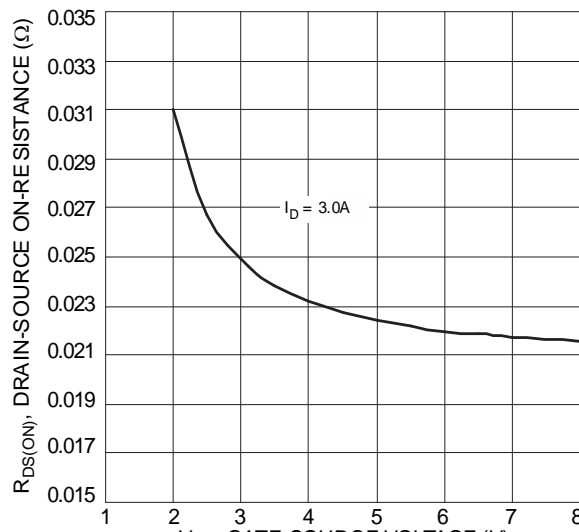
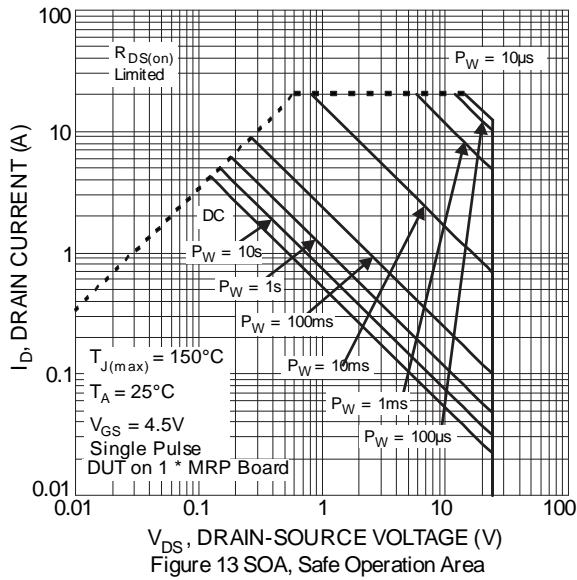
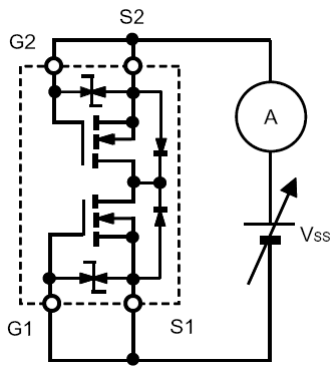


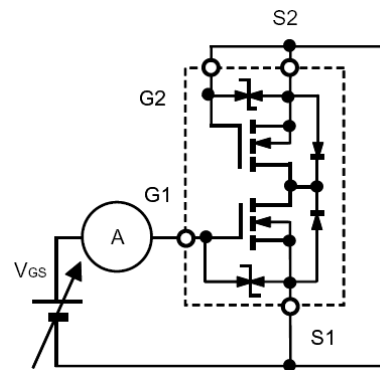
Figure 12 Typical Transfer Characteristic



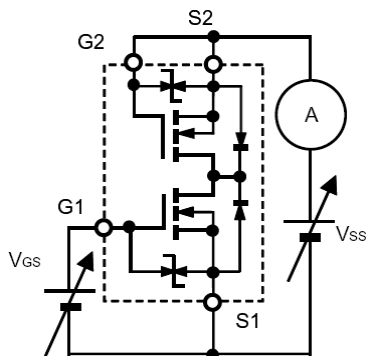
Test Circuits



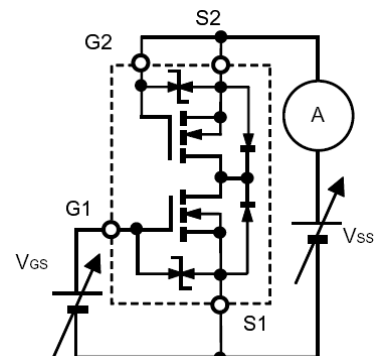
TEST CIRCUIT 1 I_{css}



TEST CIRCUIT 2 I_{gss}
When FET1 is measured, between GATE and SOURCE of FET2 are shorted.

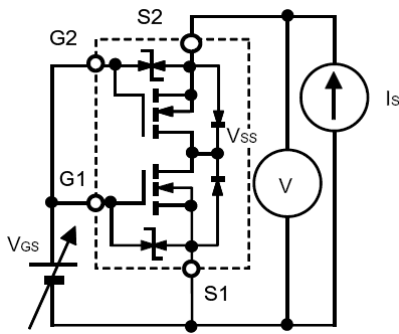


TEST CIRCUIT 3 $V_{GS(off)}$
When FET1 is measured, between GATE and SOURCE of FET2 are shorted.

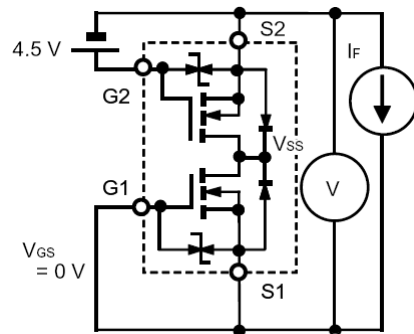


TEST CIRCUIT 4 $|y_{fs}|$
 $\Delta I_D / \Delta V_{GS}$

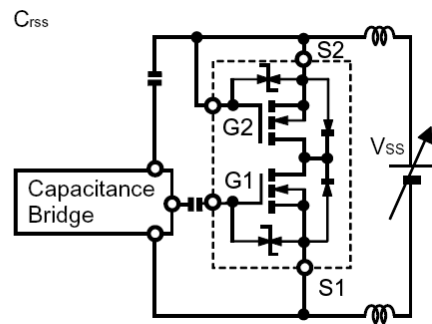
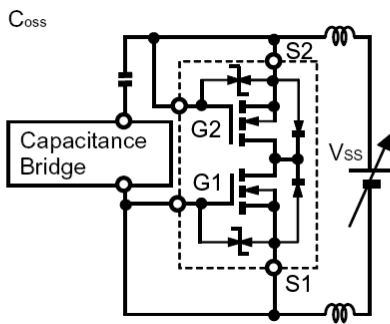
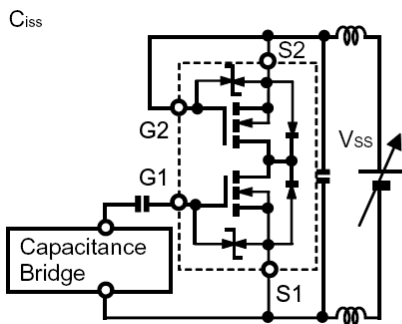
Test Circuits (cont.)



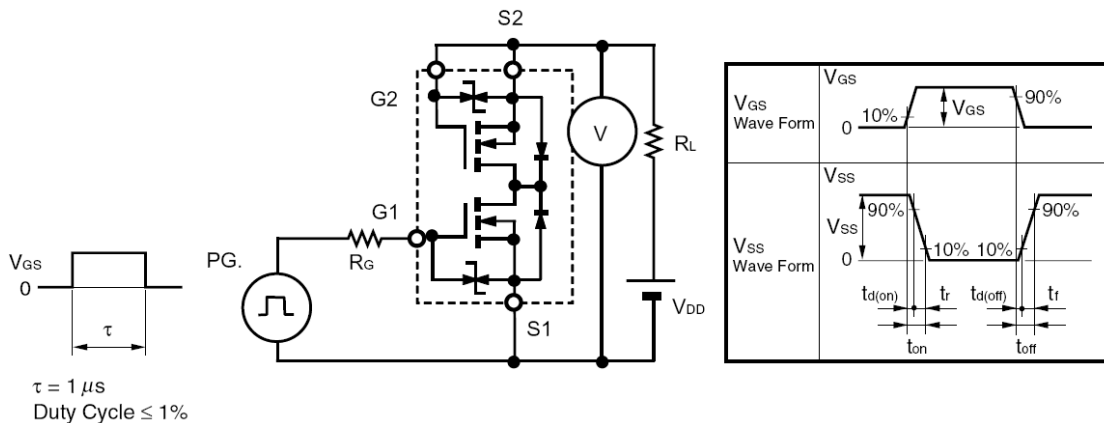
TEST CIRCUIT 5 $R_{SS(on)}$
 V_{SS}/I_S



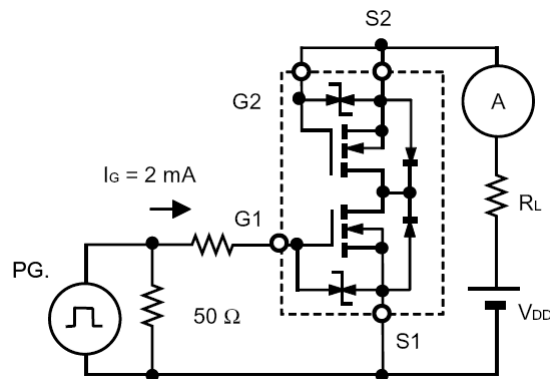
TEST CIRCUIT 6 $V_{F(S-S)}$
When FET1 is measured, FET2 is added $V_{GS} +4.5V$.



TEST CIRCUIT 7



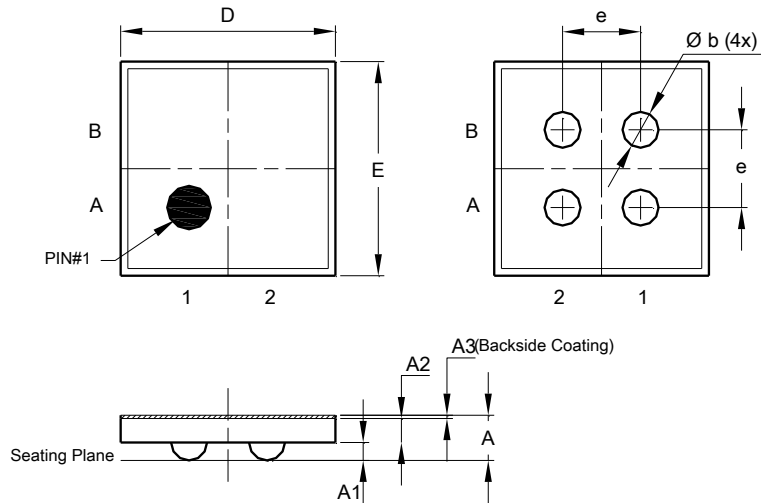
TEST CIRCUIT 8 $t_{d(on)}$, t_r , $t_{d(off)}$, t_f



TEST CIRCUIT 9 Q_G

Package Outline Dimensions

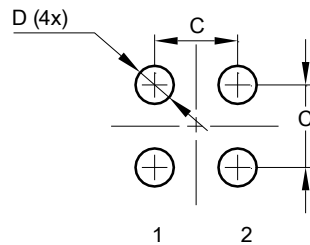
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version



| X1-WLB1818-4 | | | |
|-----------------------------|-----------|--------|--------|
| Dim | Min | Max | Typ |
| A | 0.3420 | 0.4080 | 0.3750 |
| A1 | 0.1350 | 0.1650 | 0.1500 |
| A2 | 0.1850 | 0.2150 | 0.2000 |
| A3 | 0.0220 | 0.0280 | 0.0250 |
| b | 0.2700 | 0.3300 | 0.3000 |
| D | 1.7800 | 1.8000 | 1.7900 |
| E | 1.7800 | 1.8000 | 1.7900 |
| e | 0.650 BSC | | |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| D | 0.300 |

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